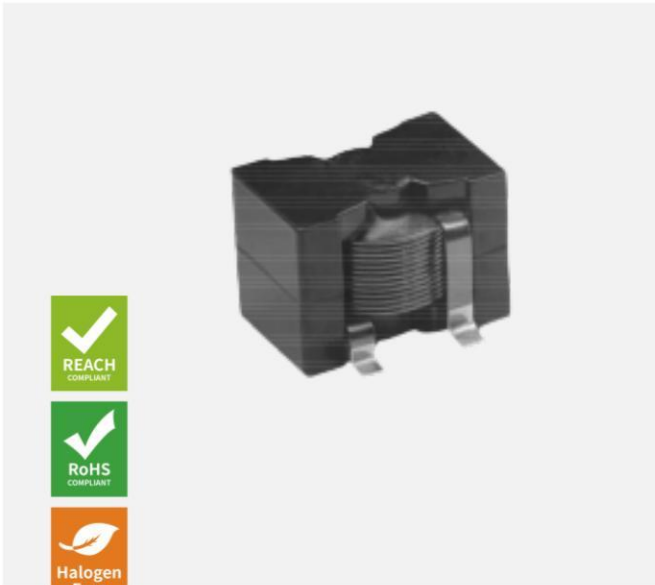


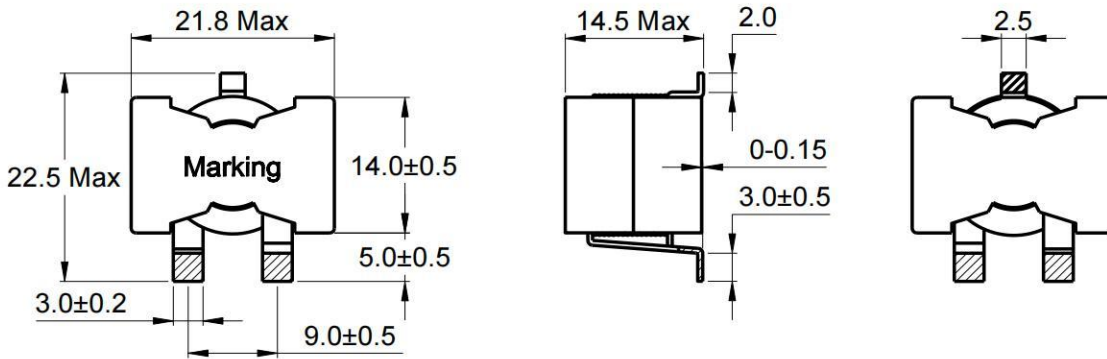


Outline: 产品概要

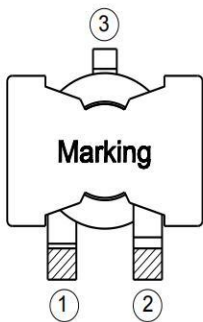
- Assemblage design, sturdy structure.
组立式设计，结构坚固。
- High inductance, high current, low magnetic loss, low ESR, small parasitic capacitance.
高电感值，大电流，低磁损，低阻抗，寄生电容小。
- Flat wire winding, achieve a low D.C. Resistance.
扁平线绕组，实现极低的直流电阻。
- Low power loss, suitable for applications of wide temperature and frequency range.
低损耗设计，适合宽频宽温环境应用。
- Operating temperature : $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$
(Including coil's temperature rise)
工作温度： $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (包含线圈发热)



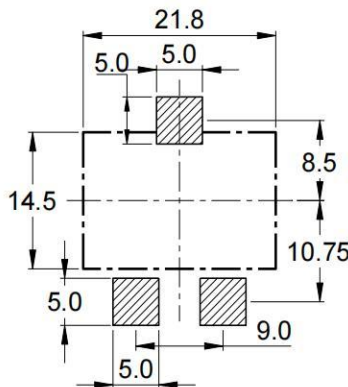
1 Appearance and Dimensions (mm) 外形尺寸(mm)



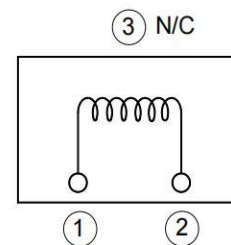
2 Marking 印字标识



3 Reference Land Pattern (mm) 参考基板尺寸 (mm)



4 Schematic 原理图



※ Date code will be changed by manufacture date.
生产日期代码将根据生产日期变动。



5 Electrical Characteristics

电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 $\pm 20\%$	D.C.R. ($\text{m}\Omega$) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max.		
CSCF2014-R70MC	0.70	0.66	0.79	75.0	32.0
CSCF2014-1R4MC	1.40	0.86	1.02	60.0	31.5
CSCF2014-2R2MC	2.20	1.32	1.58	52.0	30.5
CSCF2014-3R1MC	3.10	1.92	2.30	45.0	26.0
CSCF2014-4R2MC	4.20	2.54	3.04	38.0	24.0
CSCF2014-5R5MC	5.50	3.30	3.96	33.0	22.0
CSCF2014-7R0MC	7.00	4.25	5.10	30.0	21.0
CSCF2014-8R6MC	8.60	5.90	7.08	25.0	17.0
CSCF2014-100MC	10.0	6.50	7.80	23.0	16.0
CSCF2014-150MC	15.0	7.10	8.50	21.0	14.0
CSCF2014-220MC	22.0	8.60	10.3	15.0	12.5
CSCF2014-330MC	33.0	9.28	11.1	11.0	12.0
CSCF2014-470MC	47.0	10.0	12.0	8.50	11.5

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C 条件下测试。

※1 Inductance measure condition at 100kHz, 0.1V.

电感测试条件为 100kHz, 0.1V。

※2 Saturation current: the actual value of DC current when the inductance decrease 30% of its initial value.

饱和电流: 电感值下降其初始值的 30% 时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is $\Delta T 40^\circ\text{C}$ ($T_a = 25^\circ\text{C}$).

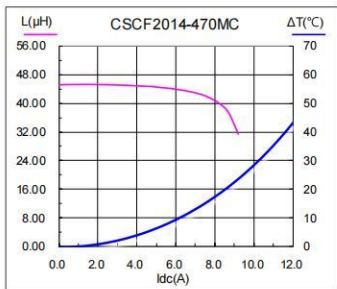
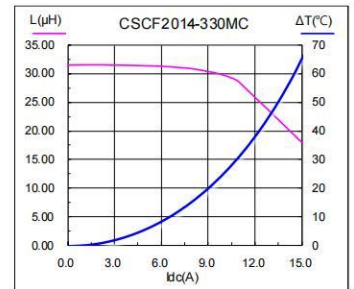
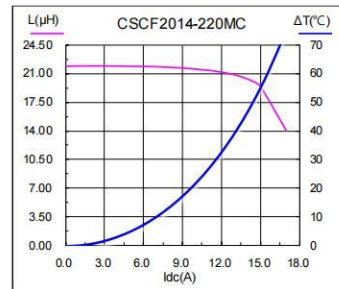
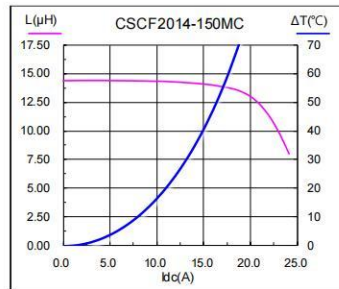
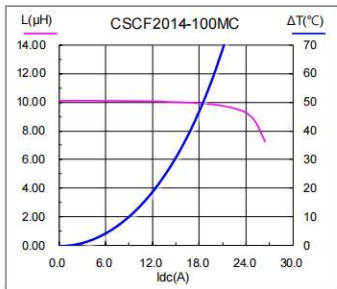
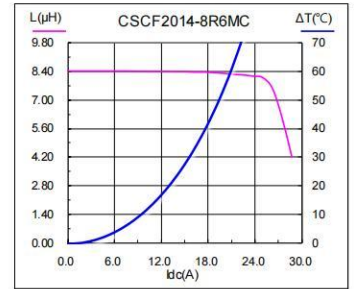
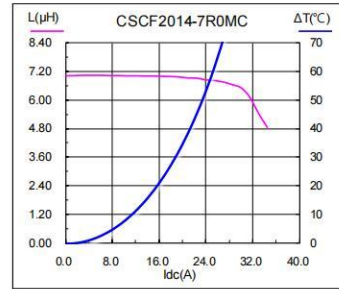
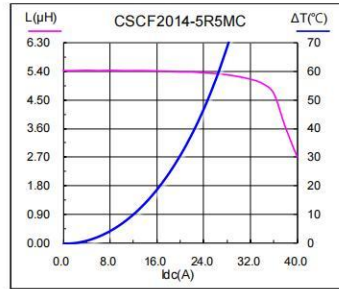
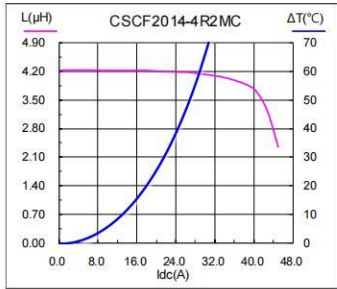
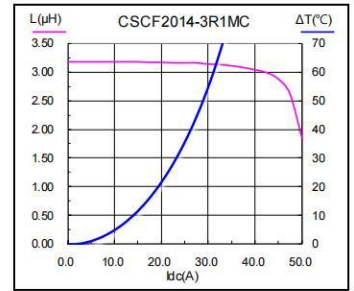
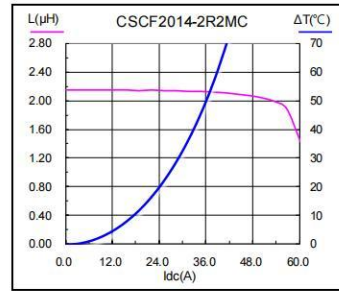
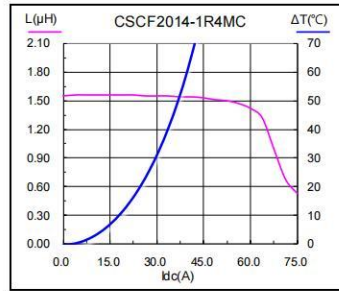
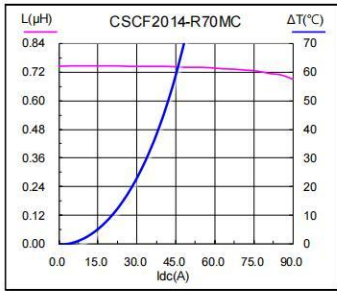
温升电流: 使产品温度上升到 $\Delta T 40^\circ\text{C}$ 时所加载的实际直流电流值 ($T_a = 25^\circ\text{C}$)。

※ Special remind: Circuit design, component placement, PCB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒: 线路设计, 组件布局, 印刷电路板 (PCB) 尺寸及厚度, 散热系统等均会影响产品温度。请务必在最终应用时, 验证产品发热状况。



6 Saturation Current vs Temperature Rise Current Curve 饱和电流 vs 温升电流曲线

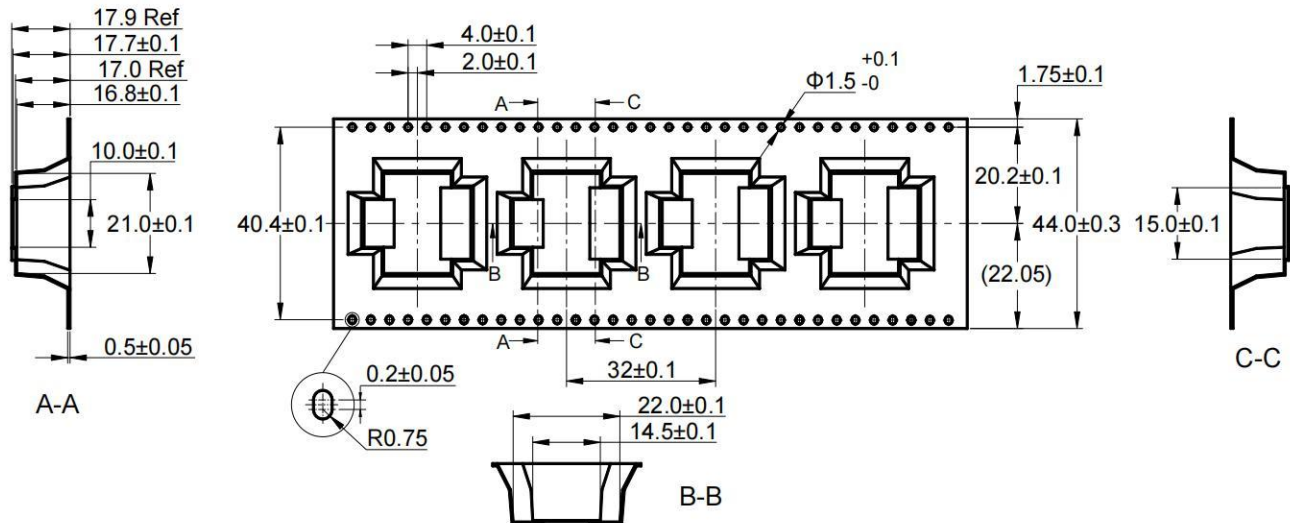


7 Packing Specification

包装规格

7.1 Carrier Tape Dimensions (mm)

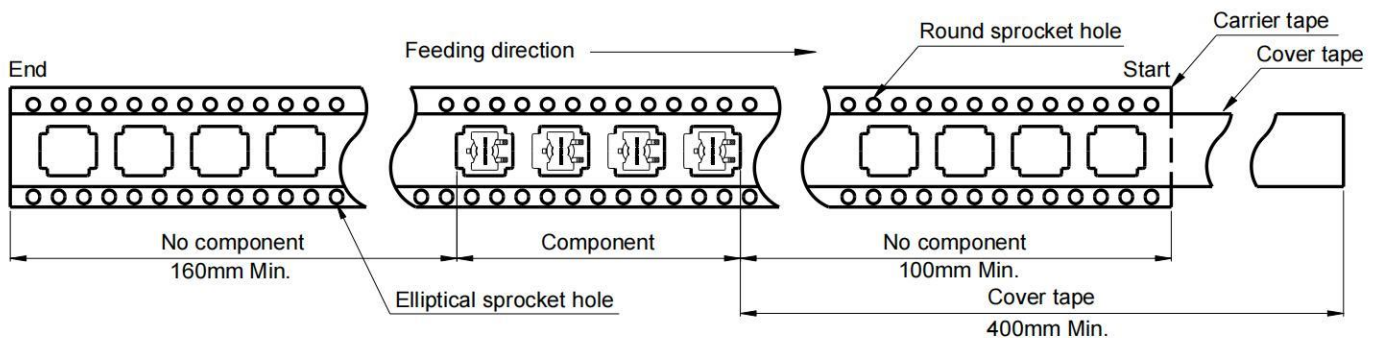
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape Direction

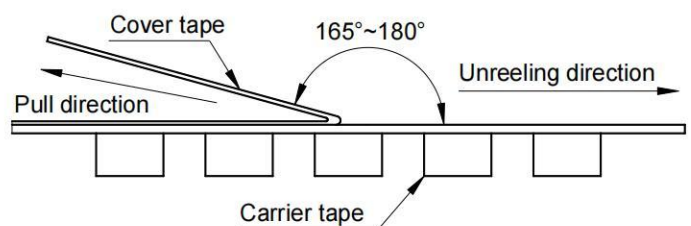
捆包方向



7.3 Cover Tape Peel Off Condition

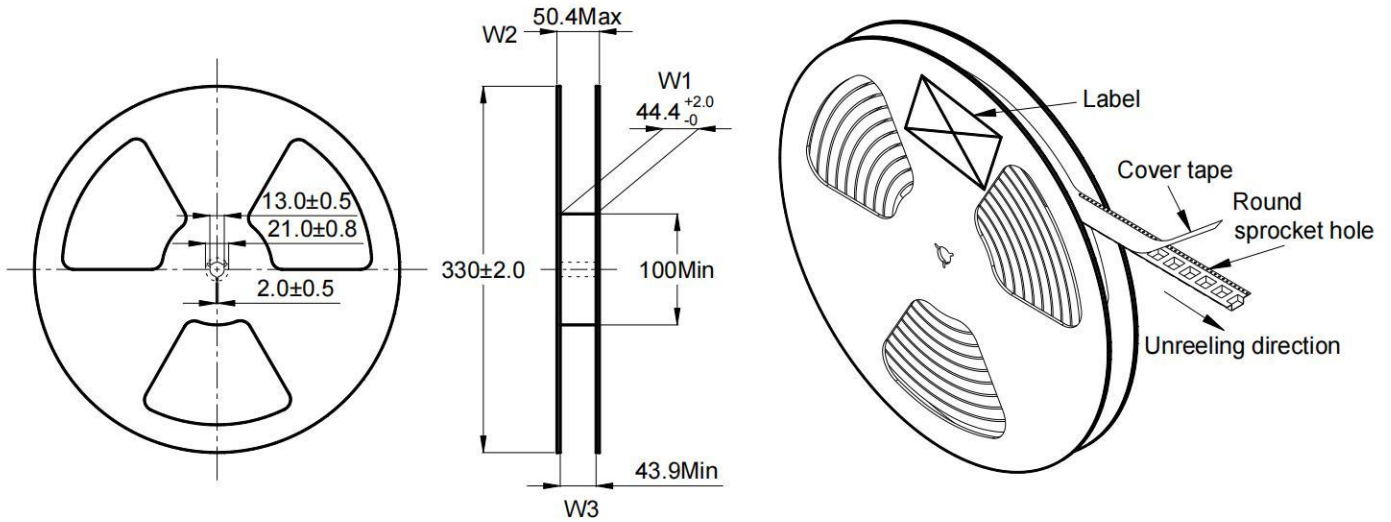
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1~1.3N。
- Reference peel speed 300±10mm/min.
参考剥离速度 300±10mm/分钟。





7.4 Reel Dimensions (mm)
卷盘尺寸



7.5 Carton Dimensions and Packing Quantity
包装箱尺寸和包装数量

■ Inner Carton: 340×340×135mm

■ Out Carton : 360×360×295mm
外包装箱

内包装盒

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSCF2014	100pcs	(100×2) = 200pcs	(200×2) = 400pcs

7.6 Label Making
标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label 产品标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

Shipping Label 运输标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

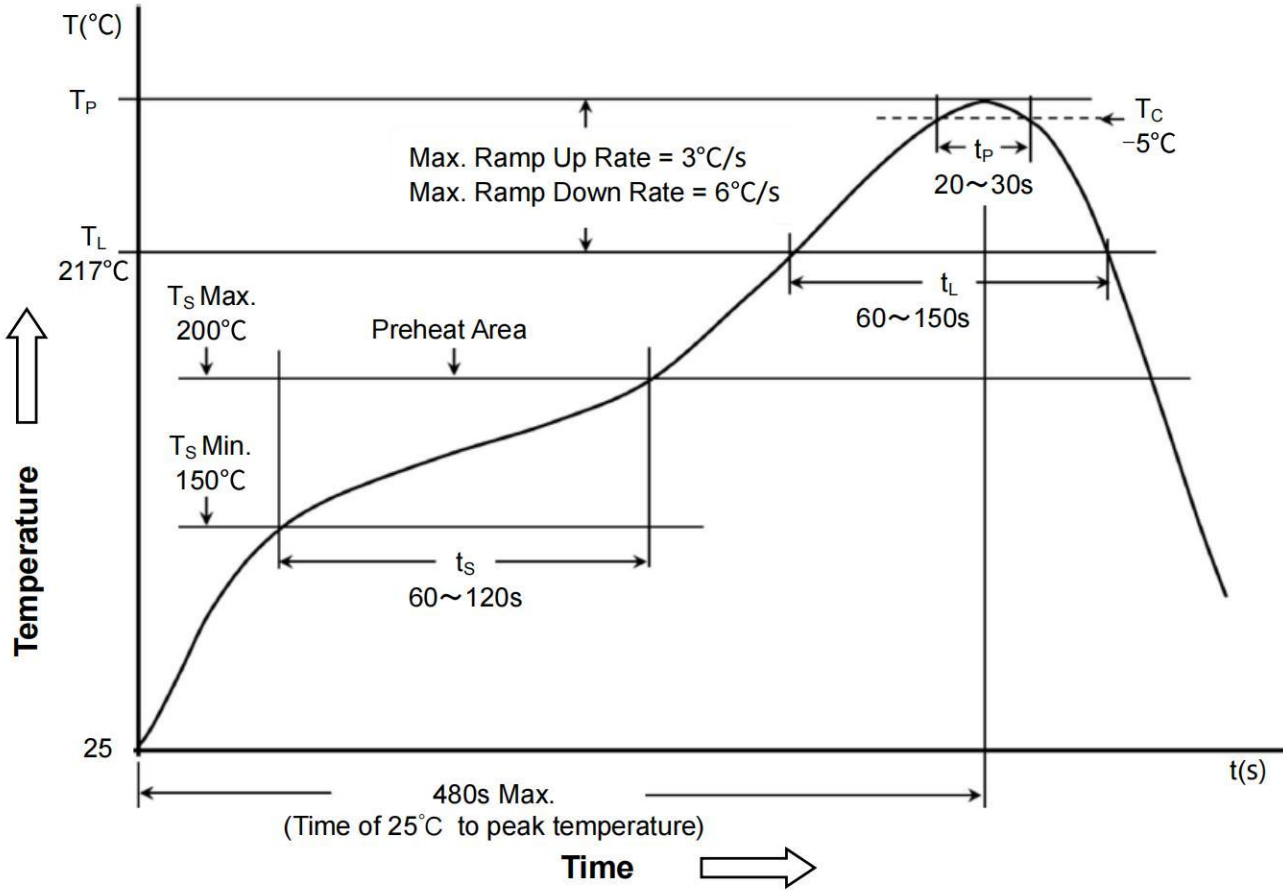


8 Soldering Specification

焊接规格

8.1 Reflow Profile for SMT Components

SMT 回流焊温度曲线



8.2 Classification of Peak Package Body Temperature (T_P)

封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D.